

A	2016-5				
B	2019-4-20				
C	2021-10-26	4			

# MMDT3906

Rev.C Oct.-2021

## / Descriptions

SOT-363 PNP

Double silicon PNP transistor in a SOT-363 Plastic Package.

## / Features

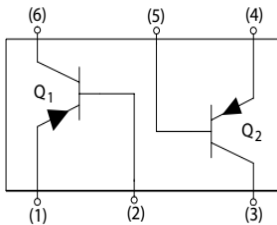
$h_{FE}$   $V_{CE(sat)}$

High DC Current Gain, Low Collector to Emitter Saturation Voltage. HF Product.

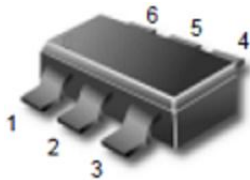
## / Applications

General purpose amplifier and switching.

## / Equivalent Circuit



## / Pinning



PIN 1 4 Emitter      PIN 2 5 Base      PIN 3 6 Collector

## / $h_{FE}$ Classifications & Marking

See Marking Instructions.

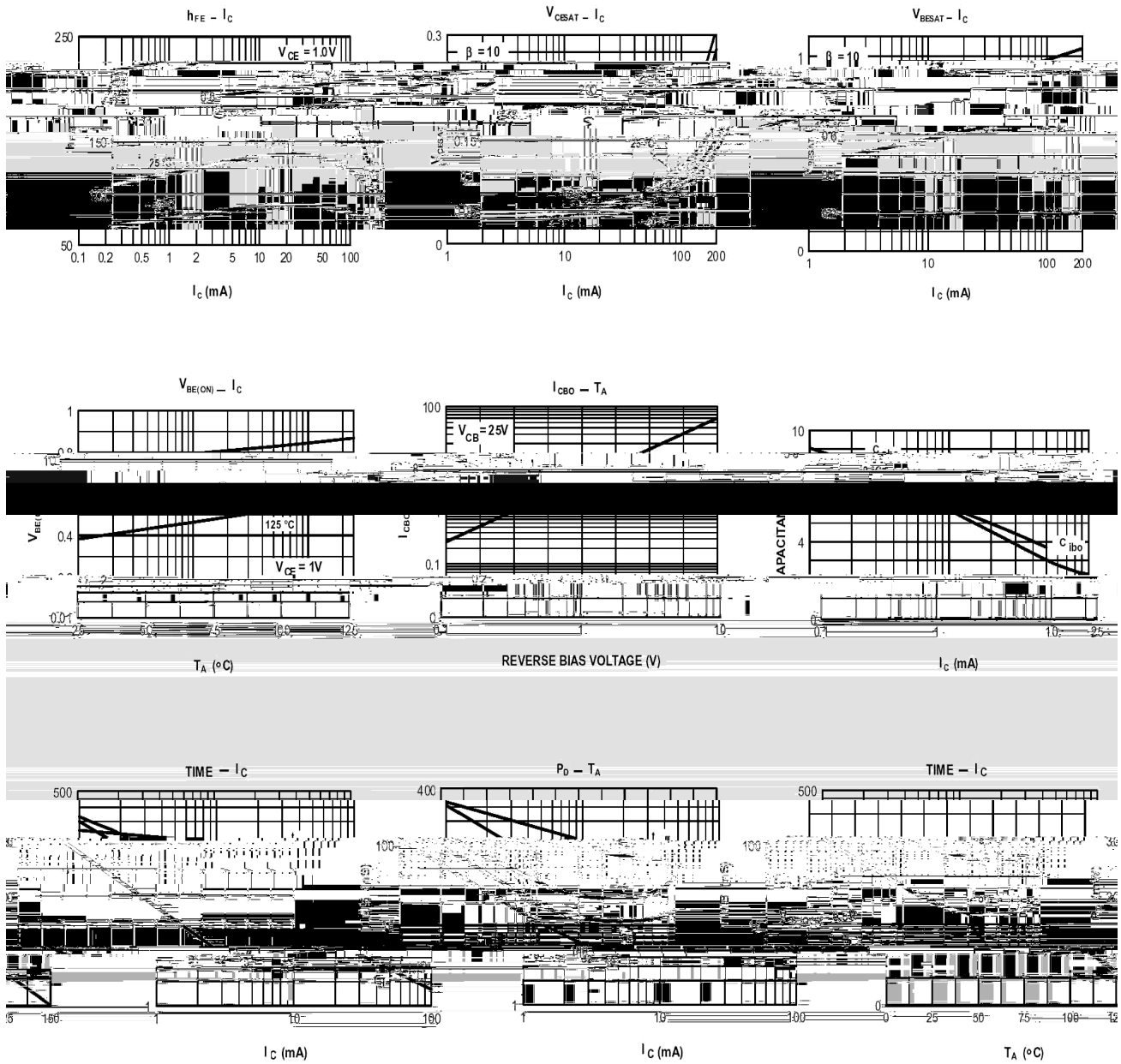
**/ Absolute Maximum Ratings(Ta=25 )**

Parameter	Symbol	Rating	Unit
Collector to Base Voltage	$V_{CBO}$	-40	V
Collector to Emitter Voltage	$V_{CEO}$	-40	V
Emitter to Base Voltage	$V_{EBO}$	-5.0	V
Collector Current	$I_C$	-200	mA
Collector Power Dissipation	$P_C$	300	mW
Junction Temperature	$T_j$	150	°C
Storage Temperature Range	$T_{stg}$	-55~150	°C

**/ Electrical Characteristics(Ta=25 )**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	$V_{CBO}$	$I_C=-10\mu A$ $I_E=0$	-40			V
Collector to Emitter Breakdown Voltage	$V_{CEO}$	$I_C=-1.0mA$ $I_B=0$	-40			V
Emitter to Base Breakdown Voltage	$V_{EBO}$	$I_E=-10\mu A$ $I_C=0$	-5.0			V
Collector Cut-Off Current	$I_{CBO}$	$V_{CB}=-30V$ $I_E=0$			-0.05	$\mu A$
Emitter Cut-Off Current	$I_{EBO}$	$V_{EB}=-3.0V$ $I_C=0$			-0.05	$\mu A$
DC Current Gain	$h_{FE(1)}$	$V_{CE}=-1.0V$ $I_C=-10mA$	100		300	
	$h_{FE(2)}$	$V_{CE}=-1.0V$ $I_C=-100mA$	30			
	$h_{FE(3)}$	$V_{CE}=-1.0V$ $I_C=-50mA$	60			
	$h_{FE(4)}$	$V_{CE}=-1.0V$ $I_C=-1.0mA$	80			
	$h_{FE(5)}$	$V_{CE}=-1.0V$ $I_C=-0.1mA$	60			
Collector-Emitter Saturation voltage	$V_{CE(sat)(1)}$	$I_C=-10mA$ $I_B=-1.0mA$			-0.25	V
	$V_{CE(sat)(2)}$	$I_C=-50mA$ $I_B=-5.0mA$			-0.4	V
Base-Emitter Saturation Voltage	$V_{BE(sat)(1)}$	$I_C=-10mA$ $I_B=-1.0mA$	-0.65		-0.85	V
	$V_{BE(sat)(2)}$	$I_C=-50mA$ $I_B=-5.0mA$			-0.95	V
Transition Frequency	$f_T$	$V_{CE}=-20V$ $I_C=-10mA$ $f=100MHz$	250			MHz
Output Capacitance	$C_{ob}$	$V_{CB}=-5.0V$ $f=1.0MHz$			4.5	pF
Storage Time	$t_{stg}$	$V_{CC}=-3.0V$ $I_C=-10mA$ $I_{B1}=-I_{B2}=-1.0mA$			225	ns
Fall Time	$t_f$	$V_{CC}=-3.0V$ $I_C=-10mA$ $I_{B1}=-I_{B2}=-1.0mA$			75	ns
Delay Time	$t_d$	$V_{CC}=-3.0V$ $V_{BE}=-0.5V$ $I_C=-10mA$ $I_{B1}=-1.0mA$			35	ns
Rise Time	$t_r$	$V_{CC}=-3.0V$ $V_{BE}=-0.5V$ $I_C=-10mA$ $I_{B1}=-1.0mA$			35	ns
Input Capacitance	$C_{ib}$	$V_{EB}=-0.5V$ $f=1.0MHz$			10	pF

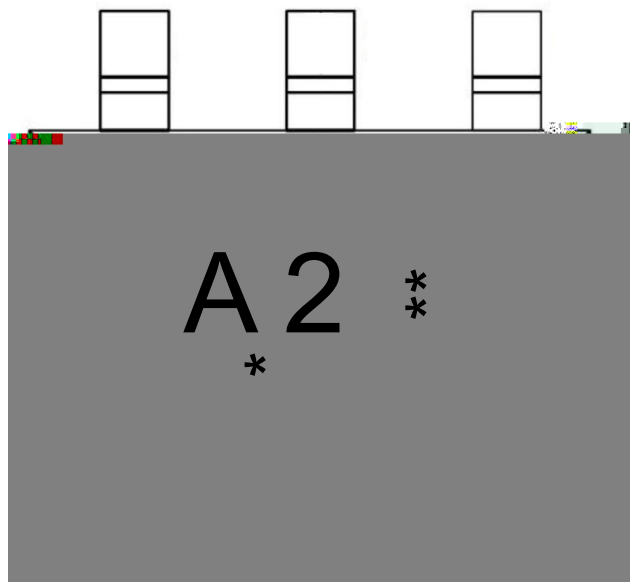
**/ Electrical Characteristic Curve**



**/ Package Dimensions**



**/ Marking Instructions**



● 1

A2

\*\*\*:

Note:

● "1" Pin

A2 Product Type Code

\*\*\*: Lot No. Code, code change with Lot No.

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)


说明：

- 1、预热温度 150~180℃，时间 60~90sec;
- 2、峰值温度 245±5℃，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2~10℃/sec.

Note:

- 1.Preheating:150~180℃, Time:60~90sec.
- 2.Peak Temp.:245±5℃, Duration:5±0.5sec.
- 3. Cooling Speed: 2~10℃/sec.

/ Resistance to Soldering Heat Test Conditions

温度：260±5℃

时间：10±1 sec.

Temp.:260±5℃

Time:10±1 sec

/ Packaging SPEC.

卷盘包装 / REEL

Package Type  
封装形式

Units 包装数量